

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	49	cohen\$-uri\$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:04
L5	4	("5,520,205" "5,365,960").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:24
L6	91	(ultrasonic megasonic) with oxide with (semiconductor wafer microfeature microelectronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:24
L8	41	(ultrasonic megasonic) with oxide with surface with (semiconductor wafer microfeature microelectronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:26
L9	154	(ultrasonic megasonic) with oxide with surface and (semiconductor wafer microfeature microelectronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:26
L10	9	(ultrasonic megasonic) with oxide with surface and (semiconductor wafer microfeature microelectronic) and ("204" "205").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:27
L11	16	(ultrasonic megasonic) with oxide with surface and (semiconductor wafer microfeature microelectronic) and electroplat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:30
L12	4	(ultrasonic megasonic) with copper adj oxide with surface and (semiconductor wafer microfeature microelectronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:31
L13	403	copper adj oxide with surface and (semiconductor wafer microfeature microelectronic) and electroplat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:31

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L14	1001	copper with oxide with surface and (semiconductor wafer microfeature microelectronic) and electroplat\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:32
L15	508	copper with oxide with surface and (semiconductor wafer microfeature microelectronic) and electroplat\$ and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:32
L16	118	copper with oxide with surface and (semiconductor wafer microfeature microelectronic) and electroplat\$ and @py<"2004" and ("204" "205").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:32
L17	28	copper with oxide with surface with remov\$3 and (semiconductor wafer microfeature microelectronic) and electroplat\$ and @py<"2004" and ("204" "205").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:37
L18	671	(ultrasonic megasonic) with (voids vias trenches opening) and (semiconductor wafer microfeature microelectronic) and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:39
L19	730	(ultrasonic megasonic) with (voids sidewall vias trenches opening) and (semiconductor wafer microfeature microelectronic) and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:39
L20	14	(ultrasonic megasonic) with (voids sidewall vias trenches opening) with (oxide) and (semiconductor wafer microfeature microelectronic) and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 15:47
L22	6	(ultrasonic megasonic) with (voids sidewall vias trenches opening) with (penetrat\$3) and (semiconductor wafer microfeature microelectronic) and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 16:07
L23	807	(ultraso\$5 megaso\$5) with (nanometer voids microvias sidewall vias trenches opening) and (semiconductor wafer microfeature microelectronic) and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 16:10
L24	2	"5544773".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 16:08

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L25	69	(ultraso\$5 megaso\$5) with (nanometer microvias sidewall vias trenches) with (activat\$3 etch\$3 microetch\$3) and (semiconductor wafer microfeature microelectronic) and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 16:19
L26	2	(ultraso\$5 megaso\$5) with (nanometer microvias sidewall vias trenches) with (wetting) and (semiconductor wafer microfeature microelectronic) and @py<"2004"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 17:30
L28	20	("20020000383" "20020020621" "430 4641" "4771111" "6080291" "6176992 " "6179983" "6228232" "6432821" "65 34116").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 17:31
L29	1	("20020000383" "20020020621" "430 4641" "4771111" "6080291" "6176992 " "6179983" "6228232" "6432821" "65 34116").PN. and (ultraso\$5 megaso\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 17:31
L30	1	("20020000383" "20020020621" "430 4641" "4771111" "6080291" "6176992 " "6179983" "6228232" "6432821" "65 34116").PN. and (ultraso\$5 megaso\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/17 17:31